These assemblies are ESD sensitive. ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

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<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
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<td>GENERATED : 9/24/2015 10:30:15 AM</td>
<td>TEXAS INSTRUMENTS</td>
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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PLOT NAME = Bottom Assembly Drawing  
GENERATED: 9/24/2015 10:30:15 AM  
TEXAS INSTRUMENTS
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